ABSTRACT

In a process for manufacturing a semiconductor device comprising heating a wiring board on which a chip and an uncured adhesive layer are laminated for curing the adhesive layer, the improvement includes performing a statically pressurizing step before the adhesive layer is cured, in which step the wiring board on which the chip and the uncured adhesive layer are laminated is subjected to a static pressure greater than atmospheric pressure by not less than 0.05 MPa. According to the invention, voids are easily eliminated irrespective of a design of the wiring board, and the adhesive is prevented from curling up on the chip.